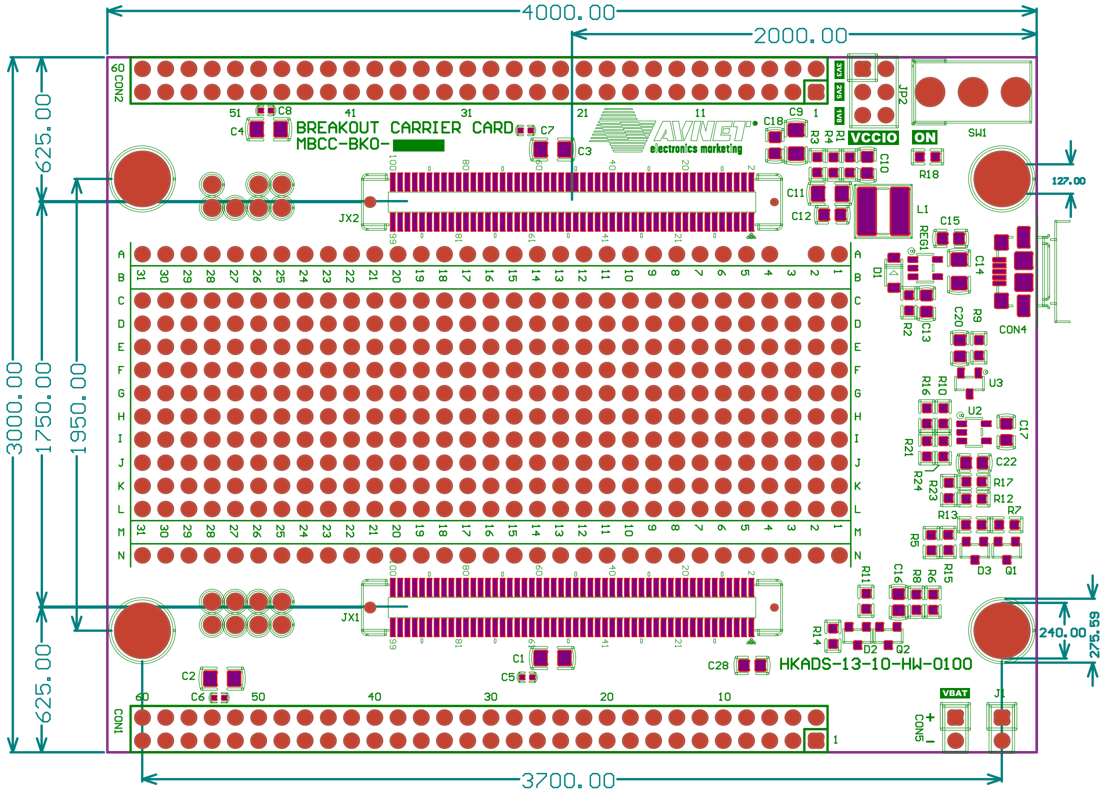
MBCC-BKO-A HKADS-13-10-HW-0100
Ref Sch: V-A 11/14/2013 2:59:11 PM
Board Thickness: 1.6mm 2 Layers FR4

	Top Solder	Top Paste
Keep-Out Layer	Mechanical 1 Mechanical 2	Top Overlay

Board shall be fabricated to Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL940V-0,
0.5 OZ Copper for External Layers & 0.5 OZ Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
Td Rating: >340 DEG C
Z Axis CTE < 3.5%
Tg > 170 DEG C (Min)

Solder Mask: SMOBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Min to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)
Finish: Electro-less Nickel Immersion Gold (ENIG), 2~8 Micro Inches Gold Over 150~250 Mirco Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.



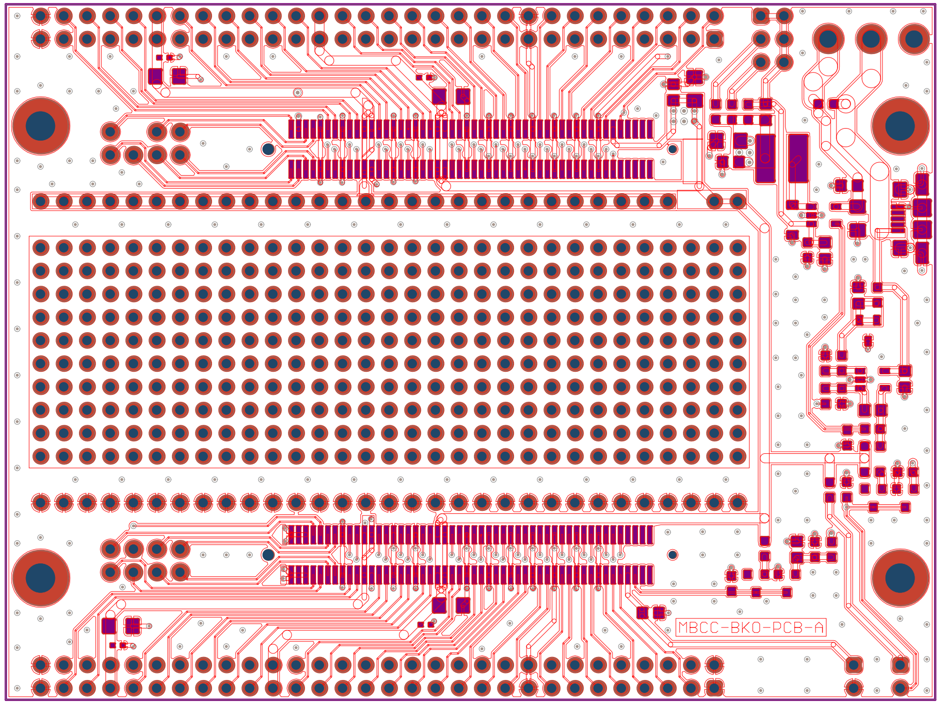
MBCC-BKO-A HKADS-13-10-HW-0100
Ref Sch: V-A 11/14/2013 2:59:12 PM
Board Thickness: 1.6mm 2 Layers FR4

Top Layer Top Solder Top Paste

Keep-Out Layer Mechanical 1

Board shall be fabricated to Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL940V-0,
0.5 OZ Copper for External Layers & 0.5 OZ Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
Td Rating: >340 DEG C
Z Axis CTE < 3.5%
Tg > 170 DEG C (Min)

Solder Mask: SMOBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Min to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)
Finish: Electro-less Nickel Immersion Gold (ENIG), 2~8 Micro Inches Gold Over 150~250 Mirco Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.



MBCC-BKO-A HKADS-13-10-HW-0100
Ref Sch: V-A 11/14/2013 2:59:12 PM
Board Thickness: 1.6mm 2 Layers FR4

Bottom Layer
Keep-Out Layer
Bottom Solder
Mechanical 1
Bottom Paste
Bottom Overlay

Board shall be fabricated to Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL940V-0,
0.5 OZ Copper for External Layers & 0.5 OZ Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
Td Rating: >340 DEG C
Z Axis CTE < 3.5%
Tg > 170 DEG C (Min)

Solder Mask: SMOBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Min to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)
Finish: Electro-less Nickel Immersion Gold (ENIG), 2~8 Micro Inches Gold Over 150~250 Mirco Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.